

Biography

Richard Matz received his diploma and Ph.D. degrees in physics from the Technical University of Aachen, Germany. He spent two years as a Postdoctoral Visiting Scientist at the IBM Thomas J. Watson Research Center, Yorktown Heights, working on diffusion barriers in silicon technology.

In 1984 he joined the Corporate Technology Division of Siemens, Munich, to develop laser materials processing on III-V semiconductors and photonic integrated circuits based on InP. He was technical supervisor of the development of the first monolithically integrated optoelectronic transceiver chip. He also made scientific contributions in the field of II-VI semiconductors to the understanding of direct-conversion X-ray detectors for computed tomography. He has authored or coauthored several book chapters and many dozens of publications in refereed journals, primarily on optoelectronic wafer fabrication and semiconductor devices.

Dr. Matz is currently competence field manager for ceramic multilayer board design and technology at Siemens Corporate Technology, with focus on wireless and lighting applications, where his developments particularly aim at the expansion of ceramic circuit boards into power electronic applications. He is member of the IEEE Components, Packaging, and Manufacturing Technology Society.

